PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data		
1.1 Company		STMicroelectronics International N.V
1.2 PCI No.		AMS/21/12698
1.3 Title of PCI		Power Management BU: Test site transfer from Amkor ATT3 to Amkor ATT6 for LDLN025xx in Flip Chip Package
1.4 Product Category		See product list
1.5 Issue date		2021-03-30

2. PCI Team		
2.1 Contact supplier		
2.1.1 Name	ROBERTSON HEATHER	
2.1.2 Phone	+1 8475853058	
2.1.3 Email	heather.robertson@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Marcello SAN BIAGIO	
2.1.2 Marketing Manager	Salvatore DI VINCENZO	
2.1.3 Quality Manager	Giuseppe LISI	

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Testing (SOP 2617)	Test site : Amkor Taiwan

4. Description of change			
Old New			
4.1 Description	Amkor Taiwan (subcon) ATT3 (T3) as Test site	Amkor Taiwan (subcon) ATT6 (T6) as Test site	
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No impact in terms of Form, Fit, Function, Reliability or Processability		

5. Reason / motivation for change		
	Following Divisional Commitments towards a continuous improvement philosophy and in agreement with Amkor testing strategy, this transfer guarantees the expansion of test space and consolidates al testers' process in same location, allowing to increase efficiency and production capacity.	
5.2 Customer Benefit	SERVICE CONTINUITY	

6. Marking of parts / traceability of change		
6.1 Description	By EWS Plant codification (from 996R AMKOR ATT3, to 9936 AMKOR ATT6) and internal traceability. No product codification change. T6 is added as 2nd EWS test plant into the ST EWS Instructions form	

7. Timing / schedule		
7.1 Date of qualification results	2021-03-23	
7.2 Intended start of delivery	2021-04-30	
7.3 Qualification sample available?	Upon Request	

8. Qualification / Validation			
8.1 Description	12698 Report.zip		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2021-03-30

9. Attachments (additional documentations)

12698 Public product.pdf 12698 Report.zip

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	LDLN025J12R	
	LDLN025J18R	
	LDLN025J25R	
	LDLN025J28R	
	LDLN025J30R	
	LDLN025J32R	
	LDLN025J33R	



Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCI Title : Power Management BU: Test site transfer from Amkor ATT3 to Amkor ATT6 for LDLN025xx in Flip Chip Package *PCI Reference :* AMS/21/12698

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

LDLN025J32R	LDLN025J25R	LDLN025J18R
LDLN025J30R	LDLN025J12R	LDLN025J33R
LDLN025J28R		

IMPORTANT NOTICE - PLEASE READ CAREFULLY

Subject to any contractual arrangement in force with you or to any industry standard implemented by us, STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2018 STMicroelectronics - All rights reserved